

FEATURES

- Low gate charge
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- RoHS product

APPLICATIONS

- High efficiency switch mode power supplies
- Electronic lamp ballasts based on half bridge
- LED power supplies

产品特性

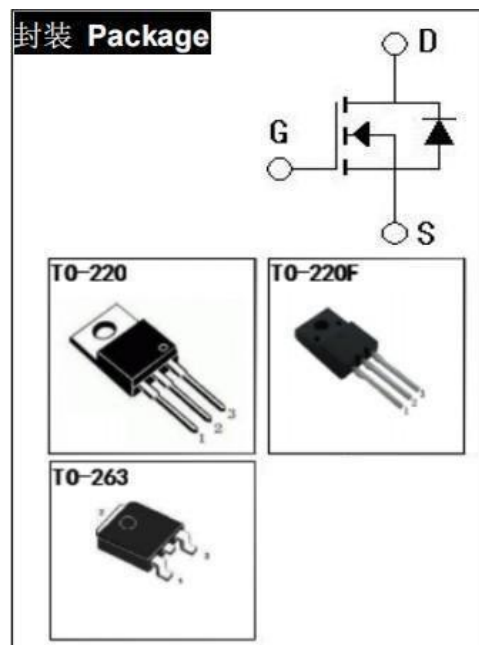
- 低栅极电荷
- 开关速度快
- 产品全部经过雪崩测试
- 高抗 dv/dt 能力
- RoHS 产品

用途

- 高频开关电源
- 电子镇流器
- LED 电源

主要参数 MAIN CHARACTERISTICS

I_D		140 A
V_{DS}		100 V
$R_{ds(on)}$ ($V_{GS}=10V$)	Typ	
	Max	4.5m Ω
Q_g -typ		98nC



产品型号信息 PRODUCT MESSAGE

型 号 Model	印 记 Marking	封 装 Package
HGS140N10C	HGS140N10C	TO-220
HGS140N10D	HGS140N10D	TO-220F
HGS140N10S	HGS140N10S	TO-263



Absolute Maximum Ratings at $T_J = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS} = 0V$)	V_{DSS}	100	V
Continuous Drain Current $T_C = 25^\circ\text{C}$ (note1)	I_D	140	A
Continuous Drain Current $T_C = 100^\circ\text{C}$ (note1)		100	A
Pulsed Drain Current (note2)	I_{DM}	450	A
Gate Source Voltage	V_{GSS}	± 20	V
Single Pulse Avalanche Energy (note3)	E_{AS}	480	mJ
Power Dissipation $T_C = 25^\circ\text{C}$ (note4)	P_D	198	W
Operating Junction and Storage Temperature Range	T_J, T_{slg}	-55~175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (note1)	$R_{\theta JC}$	0.42	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient (note1)	$R_{\theta JA}$	62	

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

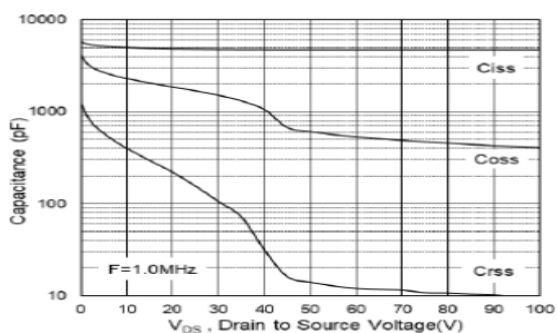


Fig.7 Capacitance

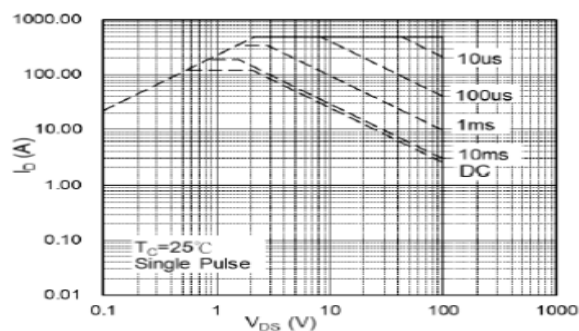


Fig.8 Safe Operating Area

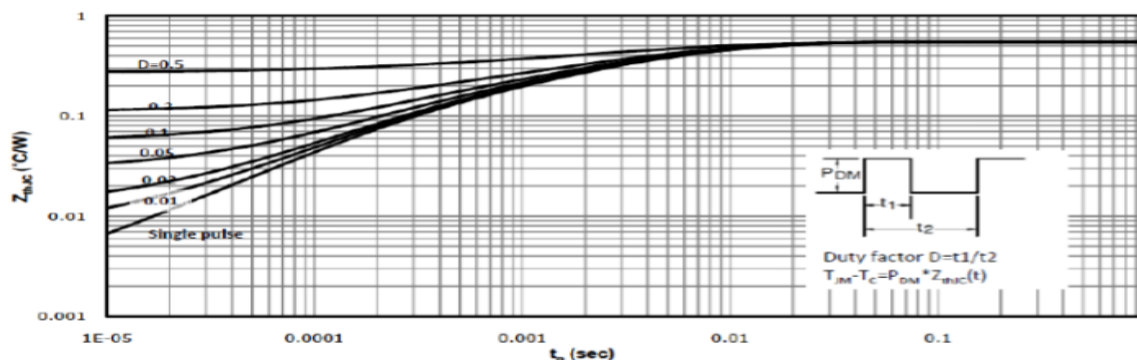


Fig.9 Normalized Maximum Transient Thermal Impedance



HGS140N10 N-CHANNEL MOSFET

Electrical Characteristics $T_J=25^{\circ}\text{C}$ unless otherwise specified						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	100	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100\text{V}, V_{GS}=0\text{V}, T_J=25^{\circ}\text{C}$	--	--	1	μA
		$V_{DS}=100\text{V}, V_{GS}=0\text{V}, T_J=55^{\circ}\text{C}$	--	--	5	μA
Gate-Source Leakage	I_{GSS}	$V_{GS}=\pm 20\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2	--	4	V
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS}=10\text{V}, I_D=60\text{A}$	--	4.2	4.5	m Ω
		$V_{GS}=10\text{V}, I_D=2\text{A}$	--	3.9	4.3	
Dynamic						
Input Capacitance	C_{iss}	$V_{GS}=0\text{V},$ $V_{DS}=50\text{V},$ $f=1.0\text{MHz}$	--	5987	--	pF
Output Capacitance	C_{oss}		--	768	--	
Reverse Transfer Capacitance	C_{rss}		--	13	--	
Total Gate Charge (10V)	Q_g	$V_{DS}=48\text{V}, I_D=20\text{A},$ $V_{GS}=10\text{V}$	--	98	--	nC
Gate-Source Charge	Q_{gs}		--	19	--	
Gate-Drain Charge	Q_{gd}		--	27	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=30\text{V}, I_D=30\text{A}$ $V_{GS}=10\text{V}, R_G=3\Omega$	--	31	--	ns
Turn-on Rise Time	t_r		--	9	--	
Turn-off Delay Time	$t_{d(off)}$		--	85	--	
Turn-off Fall Time	t_f		--	23	--	
Body Diode Characteristics						
Source-Drain Current(Body Diode)	I_{SD}		--	--	140	A
Pulsed Source-Drain Current(Body Diode)	I_{SDM}		--	--	450	A
Body Diode Voltage	V_{SD}	$T_J=25^{\circ}\text{C}, I_{SD}=1\text{A}, V_{GS}=0\text{V}$	--	--	1.3	V
Reverse Recovery Time	t_{rr}	$T_J=25^{\circ}\text{C}$ $I_F=30\text{A}$ $di_F/dt=100\text{A}/\mu\text{s}$	--	95	--	ns
Reverse Recovery Charge	Q_{rr}		--	265	--	nC

Notes

1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The E_{AS} data shows Max. rating . The test condition is $V_{DD} = 50V, V_{GS} = 10V, L = 1mH$
4. The power dissipation is limited by 175 $^\circ\text{C}$ junction temperature
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

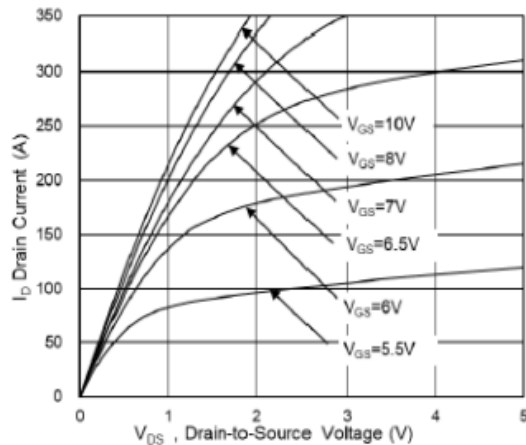


Fig.1 Typical Output Characteristics

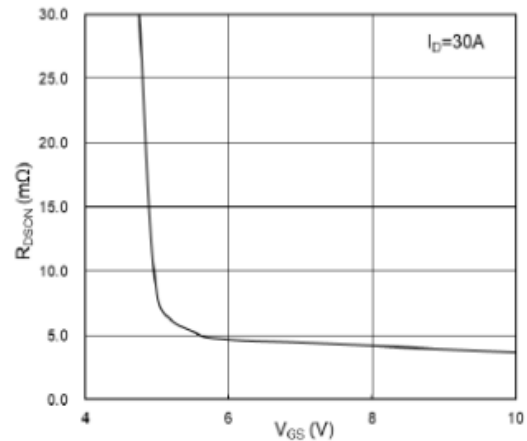


Fig.2 On-Resistance v.s Gate-Source

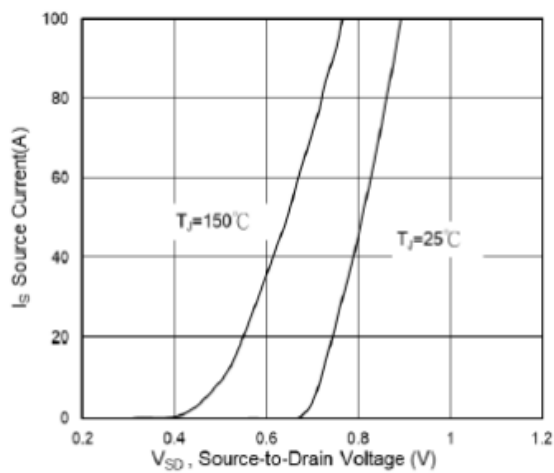


Fig.3 Forward Characteristics of Reverse

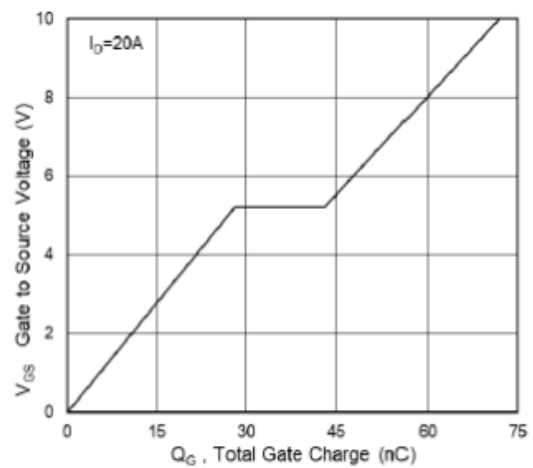


Fig.4 Gate-Charge Characteristics

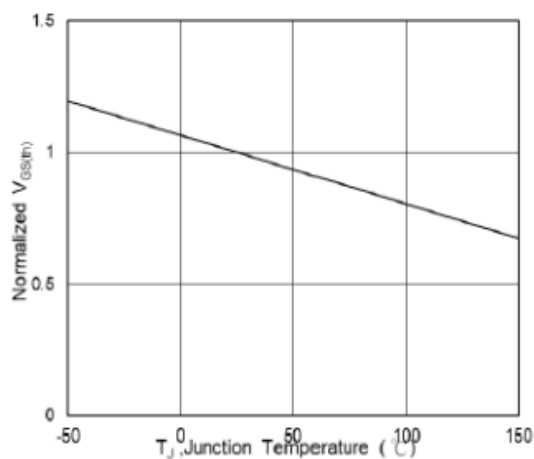


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

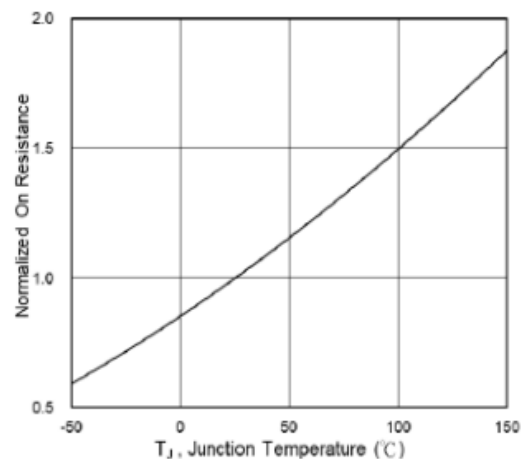


Fig.6 Normalized $R_{DS(on)}$ vs. T_J



Figure A: Gate Charge Test Circuit and Waveform

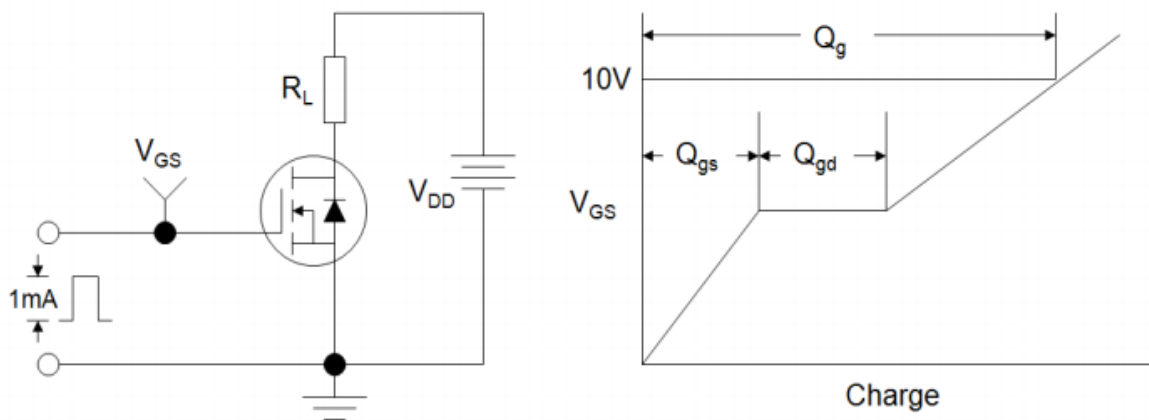


Figure B: Resistive Switching Test Circuit and Waveform

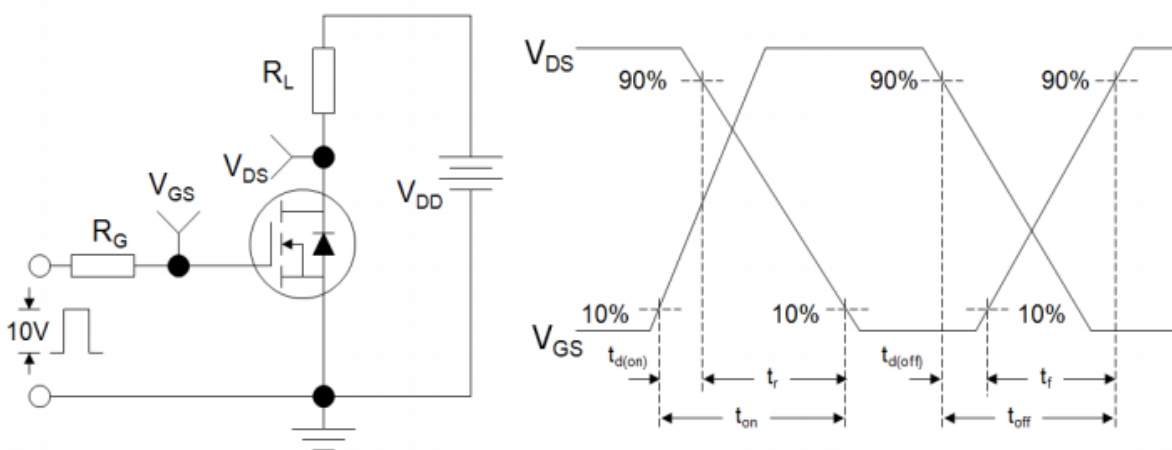
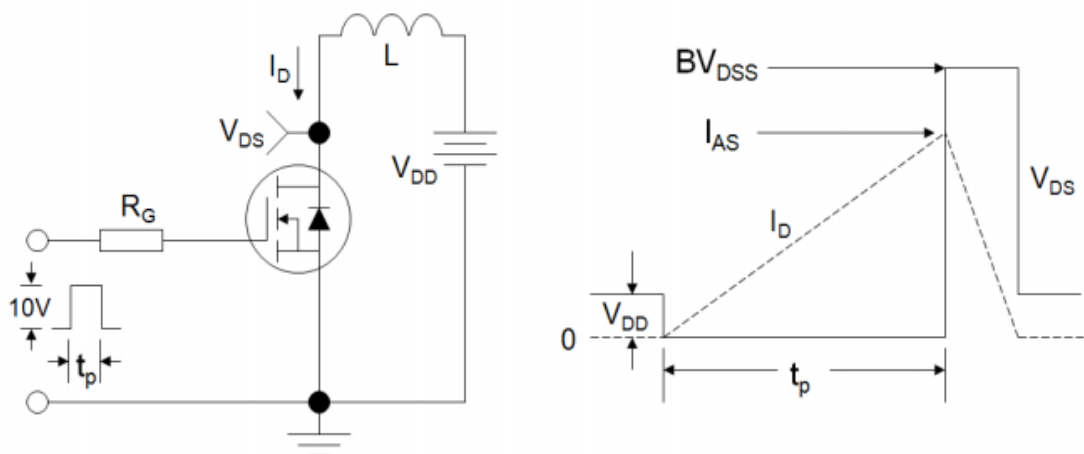


Figure C: Unclamped Inductive Switching Test Circuit and Waveform

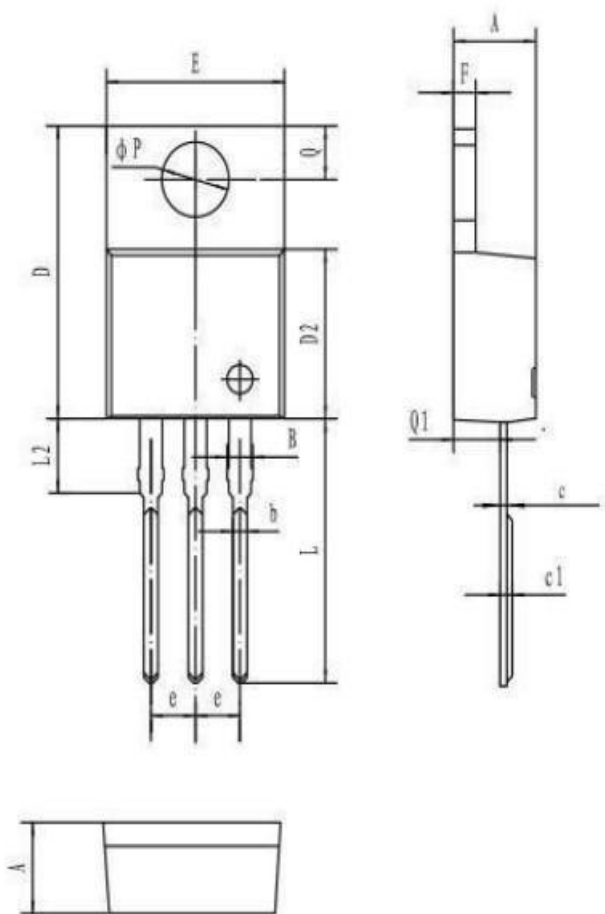




外形尺寸 PACKAGE MECHANICAL DATA

TO-220

单位 Unit : mm



符号 symbol	MIN	MAX
A	4.40	4.80
B	1.10	1.40
b	0.70	0.95
c	0.28	0.48
c1	0.32	0.52
D	14.45	16.00
D2	8.20	9.20
E	9.60	10.40
e	2.39	2.69
F	1.20	1.35
L	13.05	14.05
L2	3.70	3.90
Q	2.40	3.00
Q1	2.20	2.90
P	3.50	4.00



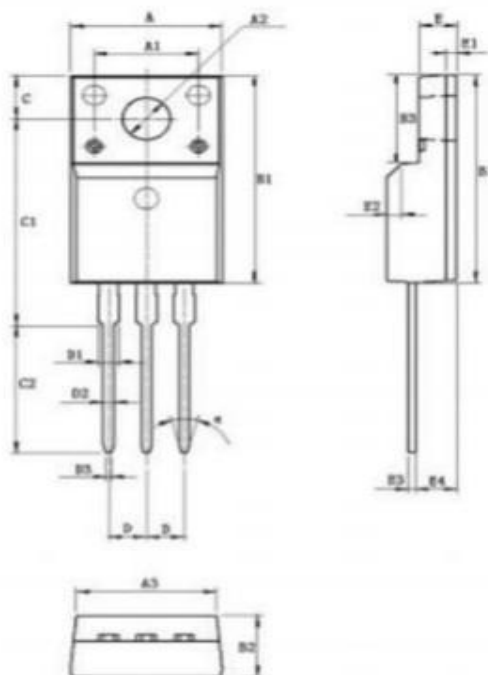
外形 寸 PACKAGE MECHANICAL DATA

TO-220F

单位 Unit : mm

Package Dimension

TO-220F



单位: mm

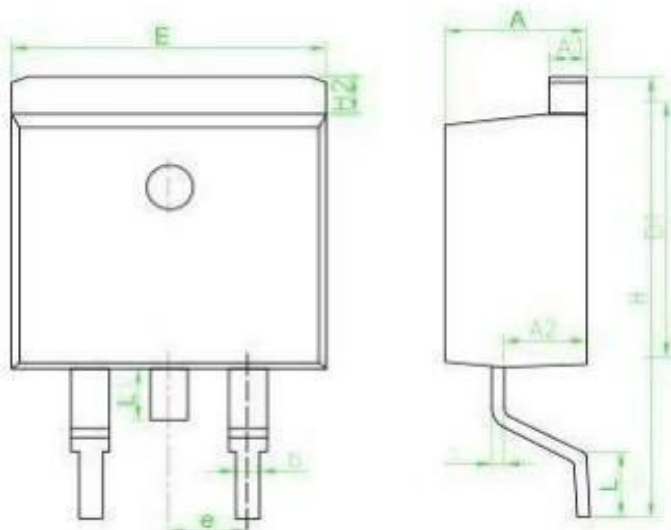
Symbol	Min	Max	Symbol	Min	Max
A	9.96	10.36	D	2.54	
A1	7.00		D1	1.15	1.35
A2	3.08	3.28	D2	0.70	0.90
A3	9.25	9.65	D3	0.28	0.48
B1	15.70	16.10	E	2.34	2.74
B2	4.50	4.90	E1	0.70	
B3	6.20	6.80	E2	1.0×45°	
C	3.20	3.40	E3	0.36	0.65
C1	15.20	16.00	E4	2.55	2.95
C2	9.75	10.15	a(度)	30°	

外形尺寸

PACKAGE MECHANICAL DATA

TO-263

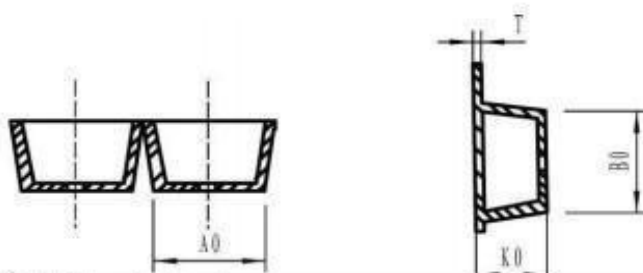
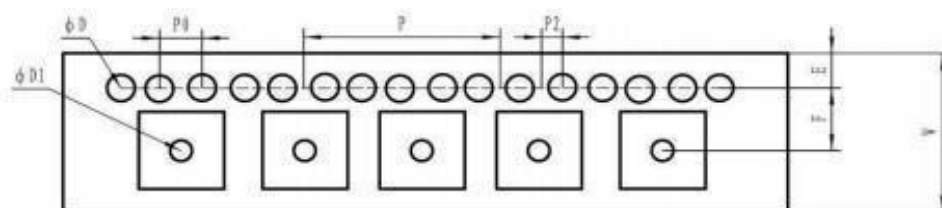
单位 Unit : mm



SYMBOL	MM.	
	MIN	MAX
A	4.30	4.80
A1	1.12	1.42
A2	2.54	2.84
b	0.67	1.00
c	0.29	0.52
D1	8.40	9.00
E	9.80	10.46
e	2.54BSC	
H	14.00	16.00
H2	1.12	1.45
L	1.50	3.10
L1	1.45	1.70

编带

REEL



产品尺寸规格 (UNIT:mm)				
规格	W	A0	E	F
尺寸	24 ±0.3	10.9 ±0.2	1.75 ±0.2	11.5 ±0.2
规格	D1	P0	P2	P
尺寸	1.5 ±0.2/-0.1	4 ±0.2	2 ±0.2	16 ±0.2
规格	K0	B0		
尺寸	4.9 ±0.2	16.0 ±0.2		



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